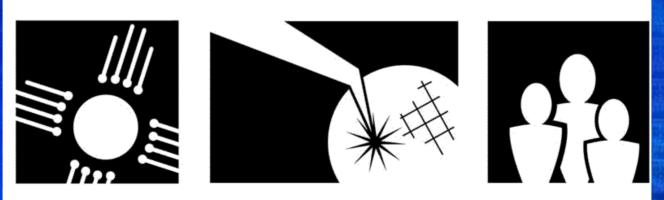
## The need for a Revolution in Test Tooling

Steven B Strauss Intel Test Tooling Operation Manager Chandler, Arizona





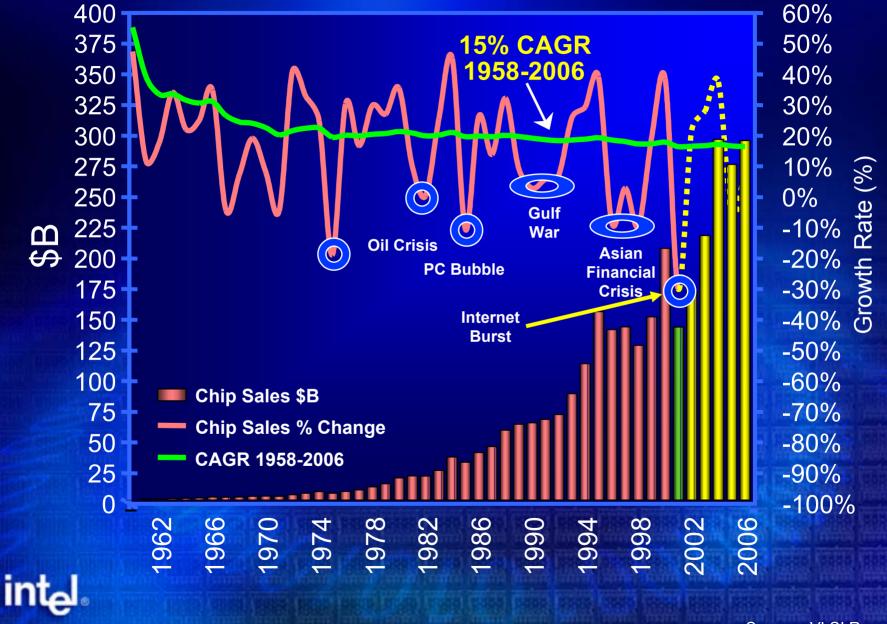
## SOUTHWEST TEST WORKSHOP

## Take Away:

- Increasing costs have driven changes in Capital Equipment for Test
- A revolution is happening in Test Equipment to respond to these costs
- The Tooling Supply industry has not changed to meet customer needs
  - comprehensive solutions, cost, leadtime or capability
- It's time for a Revolution in Test Tooling

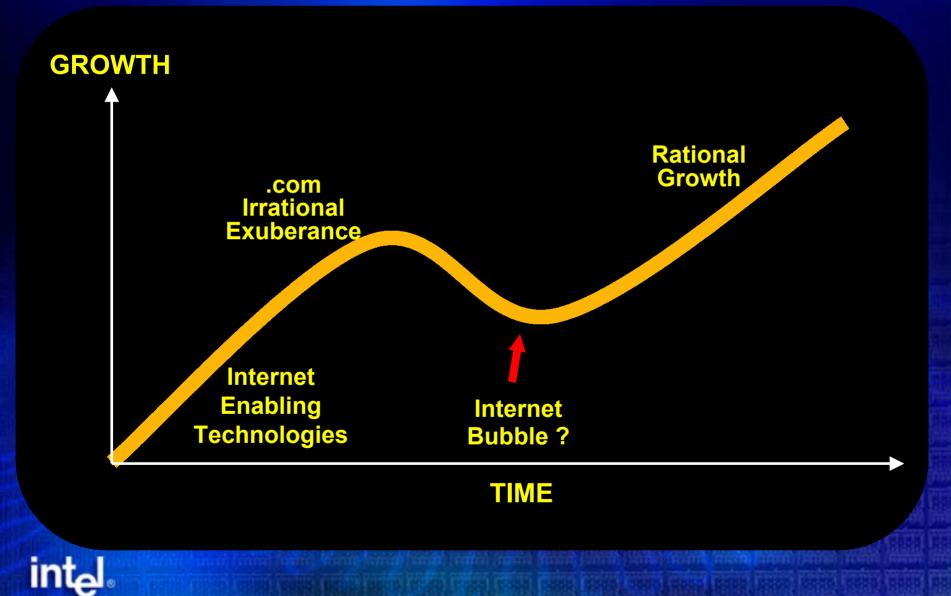


## **Semiconductor Industry Cycles**



Source: VLSI Research

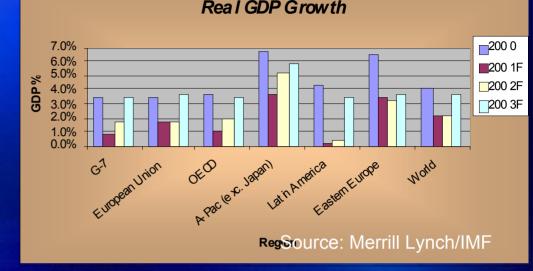
## **The Last Cycle**

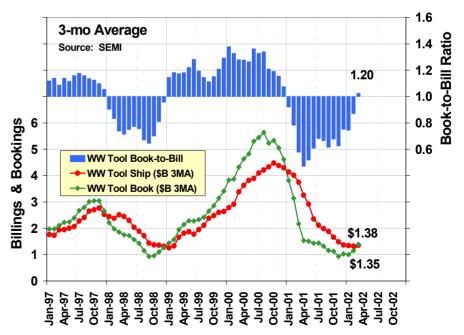


## Optimism for 2H'02 – '03

- Consumer confidence is up
- US economy predicted to grow
   3.2% in 2002
- China, South Korea, and Eastern Europe are leading
- IT dependent countries (Singapore, Taiwan) will follow by latter half
- Some economies are stuck in reverse (Argentina, Japan)
  - will they follow in 2003 ?

Will supplier improvement and responsiveness continue in the upturn?

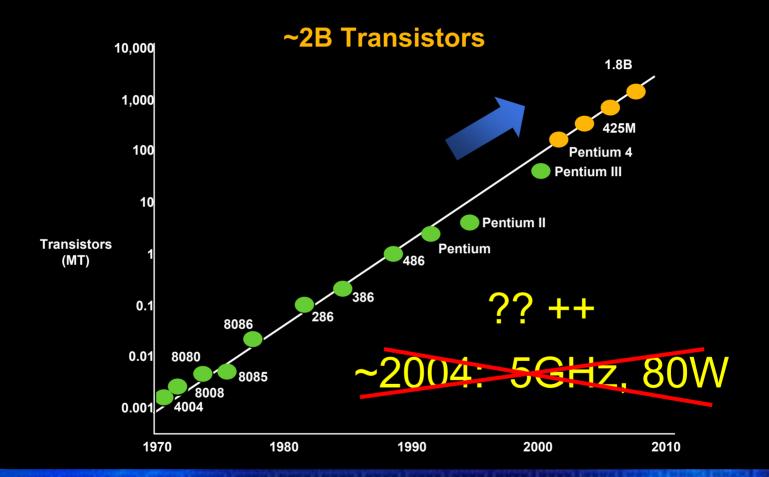




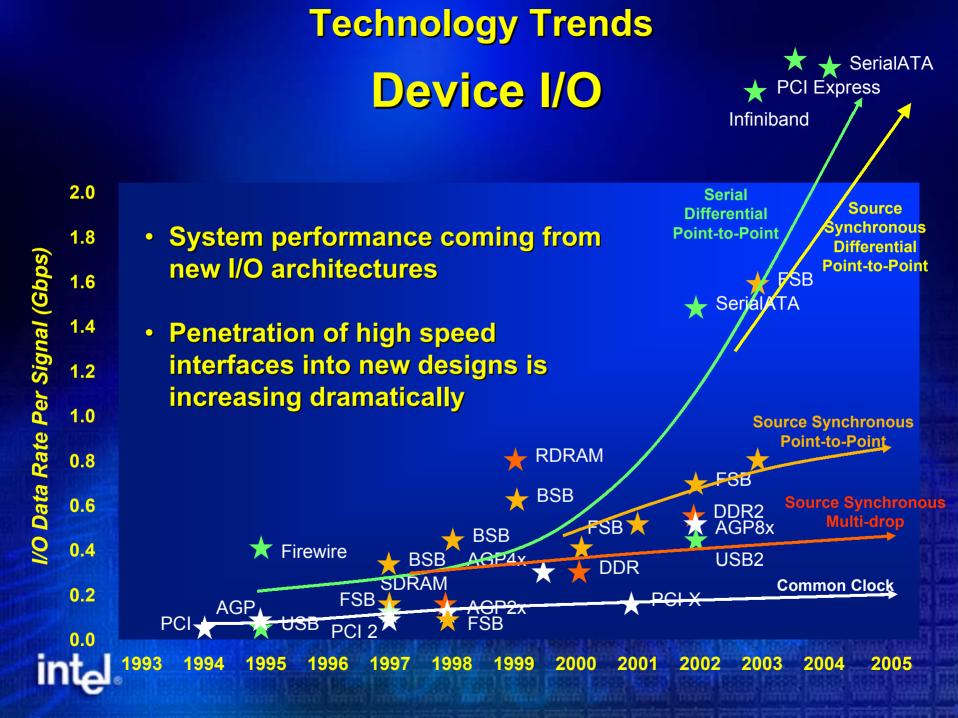
#### Worldwide Equipment Book-to-Bill

#### **Technology Trends**

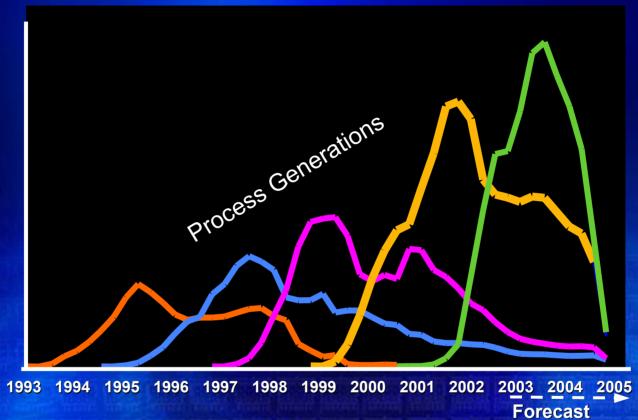
Transistors doubling every 2 years toward a billion transistors



## Q4'01 estimates for Q4'02 CPU top intel frequency was 2.5Ghz, reality will be 3Ghz +



## **The Process Lifecycle**



130nm – 4 quarters from development to HVM No time for Mistakes – HVM and Prototypes are one and the same intol.

Unit Volume

#### **The Real Product Cycle**



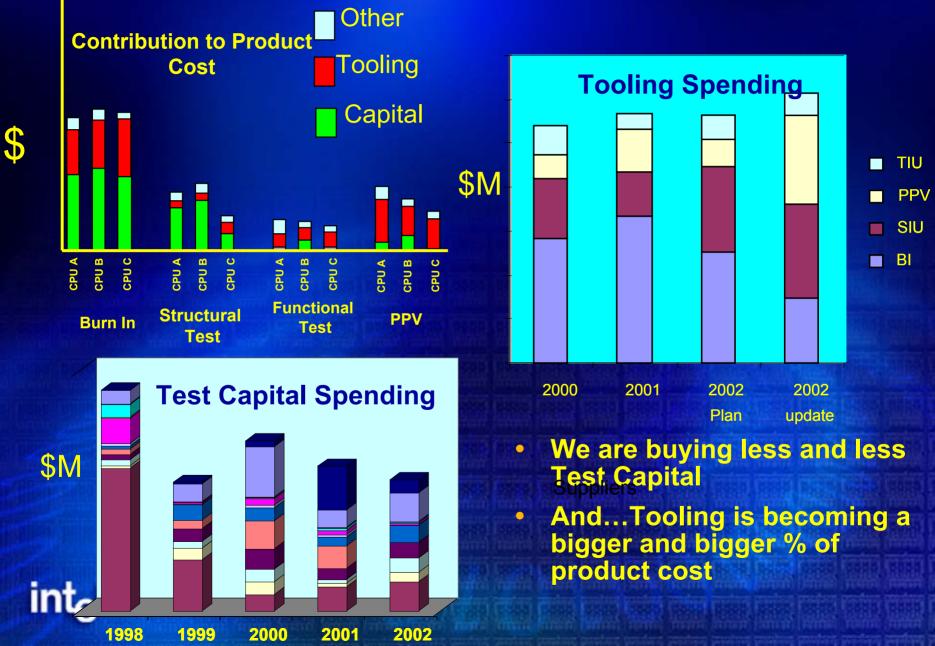
#### **Product Changes**

Speed Improvements, Yield Improvements, Packaging and other changes yield an effective product cycle of 3 to 6 months

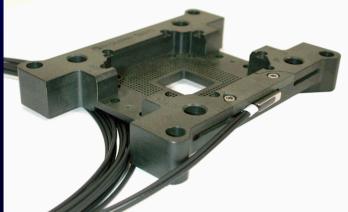
**Overlapping ramp up, peak, ramp down** 

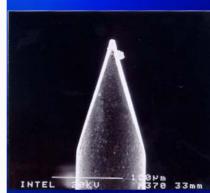
No time for Mistakes – HVM and Prototypes int\_l are one and the same

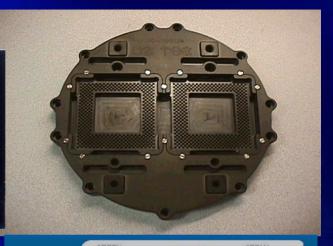
## **Capital vs. Tooling Spending**

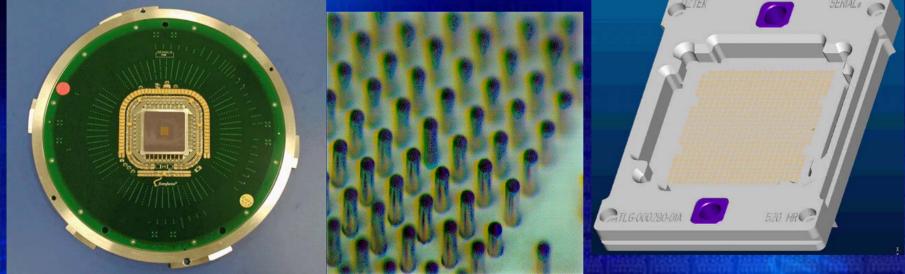


## Tooling









## intی Probe Cards, Sockets, Test Boards, BIB's...

## The tooling challenge

Provides a temporary Thermal Mechanical and/or Electrical interface to the DUT Is custom to products Customized to: Packaging form factors, **Electrical and Thermal requirements and Device** Function Demand driven by product ramp cycles **Complex supplier and supply chain logistics** And is a technology, development and **HVM** enabler!



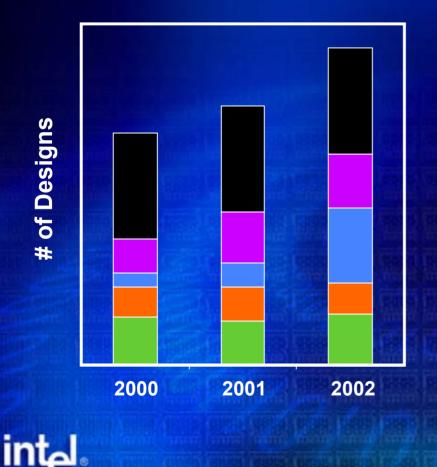
# Tooling Suppliers are not fully enabling their customers



#### Example: Probe Card **Design Outsourcing**

- Product Family A 
  Product Family D
- Product Family B <a>Product Family E</a>
- Product Family C

#



- **NPI numbers increasing**  $\bullet$
- 2001- All SIU's designed in-• house
- **Probe Card Design Growth:**  $\bullet$ 
  - 22% 2000 to 2001, 38% 2001 to 2002
- Strategy changed in 2001 to enable outsourced designs
  - >1/3 outsourced designs planned in 2002
- Intel had to enable suppliers to be able to do these designs
- These same suppliers could not provide total solutions – only designs

#### Example: Lead time reduction Only marginal improvement in 2 years



## What does a revolution look like?

## **A Tester Example**

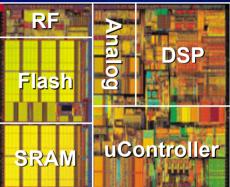


## Example Problem: SOC

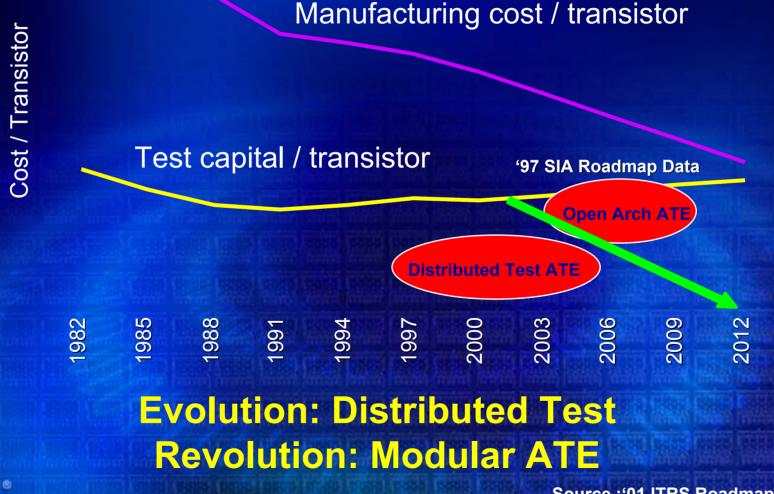
- Highly integrated device containing any combination or permutation of the following:
  - Processor Core
  - DSP Core

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- Memory Interface
- Embedded Memory (SRAM, Flash)
- Analog (ADCs, DACs, baseband, RF)
- High Speed Serial
- Peripheral Interfaces



#### Problem: Need to change the slope of the test curve



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Source :'01 ITRS Roadmap Data

### **Distributed Test Partition the test content by socket:**

Fab ↓ Structural Wafer Sort

Assembly

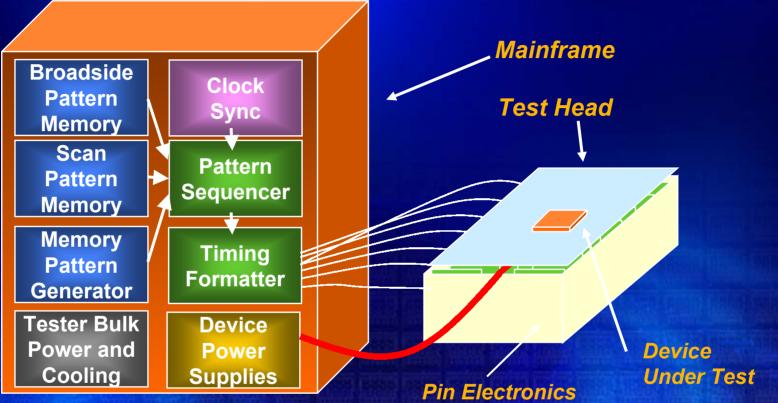
STDB

Functional Class System Test  The ATE industry has enabled this capability!

- Implemented advanced DFT to manage test complexity
- Reduce capability treadmill
- Enable parallel test in complex designs
- Move a significant percentage of test content to less expensive DFT based structural testers
  - Enables capital cost reduction
  - Deliver state-of-the-art capabilities
  - Simplified tester hardware designs
  - Optimized content and flow

Source: Intel STTD

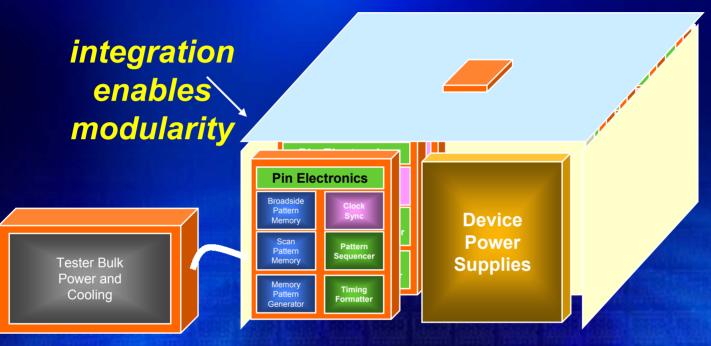
#### Modular ATE: Current Tester Architecture



- Closed architecture
- Custom infrastructure
- Difficult to support
- Improvements are 'generational' and difficult to incorporate
- intal. Single supplier

Source: Intel TCED Navid Shahriari

## Modular ATE: A small step forward



#### **Positives:**

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- Modules = "Tester on a board"
- Flexible configurations

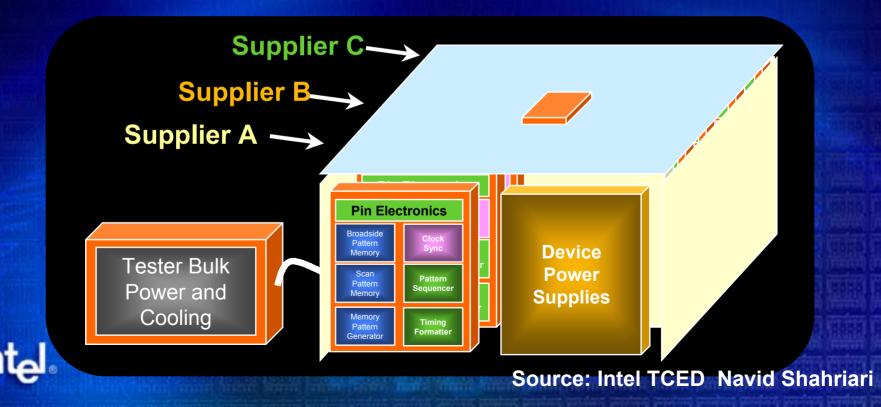
But....Still has negatives

Single supplier
Closed architecture

Source: Intel TCED Navid Shahriari

## **Revolutionary Solution:** Open Architecture VLSI ATE

- Multiple suppliers, industry specifications
- Scales across price, performance, pin counts, applications
- Reusable platforms & incremental CIP
- Standard operating system and equipment interface software
- Addresses high mix, low volume business need for "configure on the fly" capability



## **Turn Key Tooling?**

- Are there any "turn key" tooling suppliers? The tooling industry is fragmented
- The Capital Analogy:
  - Buy capital equipment One stop shopping
    - You don't buy the pieces from 2-3 suppliers!
- Lets buy a Vertical Probe Card
  - 1 supplier for Design
  - 1 supplier for PCB / Space transformer manufacturing
  - 1 supplier for Probes / Integration
- Who stands by the final product? The Customer ?

The Tooling Supply Chain Needs to provide Solutions, not components

## **Today's Tooling Supply Chain**

- Tooling suppliers fall into 2 categories
  - Component manufacturers
  - Integrators or Assemblers
- A typical tooling supply chain contains 2-4 poorly synchronized suppliers
  - Design
  - Custom component design and manufacturing
  - Assembly or Integration
  - HVM support

 This industry infrastructure will not achieve the requirements of the future products and processes



## The Next Generation Tooling Supply Chain

- Is proactively on the "treadmill"
  - Technically
  - Economically
  - Logistically
- Enables fungible designs that last multiple product generations
- Is synchronized with the specific technologies of the customers
- Provides complete turn key solutions
- Has 2 4 weak lead times, and finds innovative ways to continue to drive it down

 Is low, low cost and continues to drive costs down nt

## What it takes is Revolution

- Evolution will not yield these goals!
- The scaling treadmill that the industry has relied upon needs to be replaced by disruptive technologies
- If you want to survive you must:
  - invest in disruptive technologies
  - cannibalize your current ones
  - acknowledge that your business model will be completely different in 2 years.

Can you do this? If not you won't survive! Strauss's Prediction : About ½ of you will be around in 2 years Will you be one of them?



"The definition of insanity as doing the same thing the same way over and over again, hoping for a different result. If you want to achieve different results -**better results** -- you have to do things differently. Success is not accidental. It happens because people plan carefully and they lay the necessary groundwork to get the right result in the end."

> -- Craig Barrett President and CEO, Intel Corporation December 29, 2000



